

## CLAIMS

We claim:

1. A method of adjusting a die placement of dice to be formed on a wafer, the method comprising:
  - a) obtaining a die placement of dice to be formed on the wafer;
  - b) obtaining one or more locations on the wafer contacted by one or more processing structures or a substance emitted by one or more processing structures; and
  - c) adjusting the die placement based on the obtained one or more locations on the wafer.
2. The method of claim 1, wherein the die placement is adjusted to increase yield of the dice formed on the wafer.
3. The method of claim 2, wherein step c) of claim 1 comprises:
  - generating a plurality of die placements having different arrangements of dice;
  - determining a yield associated with each of the plurality of die placements; and
  - selecting a die placement with the highest yield from the plurality of die placements.
4. The method of claim 3, wherein yield is determined based on the number of good dice formed on the wafer.
5. The method of claim 1, further comprising:
  - d) adjusting the one or more locations on the wafer based on the die placement, wherein the die placement and the one or more locations on the wafer are adjusted together.
6. The method of claim 5, wherein the die placement and one or more locations on the wafer are adjusted to increase yield of the dice formed on the wafer.
7. The method of claim 6, wherein step c) of claim 1 and step d) of claim 5 comprise:

generating a plurality of combinations of die placement and one or more locations on the wafer;

determining a yield associated with each of the plurality of combinations of die placement and one or more locations on the wafer; and

selecting a combination of die placement and one or more locations on the wafer with the highest yield from the plurality of combinations of die placement and one or more locations on the wafer.

8. The method of claim 1, wherein the die placement includes an arrangement of reticle arrays, and wherein each reticle array includes an arrangement of dice.

9. The method of claim 1, wherein the one or more processing structures include a clamp to hold the wafer during a fabrication process.

10. The method of claim 1, wherein the one or more processing structures include a jet that emits a chemical solution or water at the wafer.

11. The method of claim 1, wherein the dice are formed on a first surface on the wafer, and wherein the one or more locations are on the first surface of the wafer or on a second surface on the wafer opposite the first surface.

12. A method of adjusting a die placement of dice to be formed on a wafer, the method comprising:

a) obtaining a die placement of dice to be formed on the wafer, the die placement having an arrangement of reticle arrays, wherein each reticle array includes an arrangement of dice to be formed on the wafer;

b) obtaining one or more locations on the wafer contacted by one or more clamps; and

c) adjusting the die placement based on the obtained one or more locations on the wafer.

13. The method of claim 12, wherein step c) of claim 12 comprises:

generating different die placements having different arrangements of reticle arrays;

determining yields associated with the different die placements; and

selecting a die placement with the highest yield from the different die placements.

14. The method of claim 12, further comprising:

d) adjusting the one or more locations on the wafer based on the die placement, wherein the die placement and the one or more locations on the wafer are adjusted together.

15. The method of claim 14, wherein step c) of claim 12 and step d) of claim 14 comprise:

generating a plurality of combinations of die placement and one or more locations on the wafer;

determining a yield associated with each of the plurality of combinations of die placement and one or more locations on the wafer; and

selecting a combination of die placement and one or more locations on the wafer with the highest yield from the plurality of combinations of die placement and one or more locations on the wafer.

16. A system of adjusting a die placement of dice, the system comprising:

a wafer on which dice are to be formed;

one or more processing structures that contact one or more locations on the wafer or emit a substance that contacts one or more locations on the wafer; and

a die placement having an arrangement of dice, the die placement adjusted based on the one or more locations on the wafer.

17. The system of claim 16, further comprising:

a plurality of die placements having different arrangements of dice to be formed on the wafer, wherein yields associated with the plurality of die placements are determined, and wherein a die placement with the highest yield is selected from the plurality of die placements.

18. The system of claim 16, wherein the one or more locations on the wafer are adjusted based on the die placement, and wherein the die placement and the one or more locations on the wafer are adjusted together.

19. The system of claim 18, further comprising:

a plurality of combinations of die placement and one or more locations on the wafer, wherein yields associated with the plurality of combinations of die placement and one or more locations on the wafer are determined, and wherein a combination of die placement and one or more locations on the wafer with the highest yield is selected from the plurality of combinations of die placement and one or more locations on the wafer.

20. The system of claim 16, wherein the one or more processing structures include:

a clamp; or

a jet that emits a chemical solution or water.